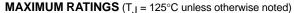
Preferred Device

Silicon Hot-Carrier Diodes

Schottky Barrier Diode

These devices are designed primarily for high-efficiency UHF and VHF detector applications. They are readily adaptable to many other fast switching RF and digital applications. They are supplied in an inexpensive plastic package for low-cost, high-volume consumer and industrial/commercial requirements. They are available in a Surface Mount package.

- Extremely Low Minority Carrier Lifetime 15 ps (Typ)
- Very Low Capacitance 1.5 pF (Max) @ V_R = 15 V
- Low Reverse Leakage $I_R = 13 \text{ nAdc (Typ)}$
- Device Marking: 4T



	Symbol	Rating	Value	Unit
Ī	V_{R}	Reverse Voltage	30	Volts

THERMAL CHARACTERISTICS

Symbol	Characteristic	Max	Unit
PD	Total Device Dissipation FR–5 Board,* T _A = 25°C	200	mW
	Derate above 25°C	1.57	mW/°C
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	635	°C/W
T _J , T _{stg}	Junction and Storage Temperature Range	-55 to +150	°C

^{*}FR-5 Minimum Pad



ON Semiconductor™

http://onsemi.com

30 VOLTS SILICON HOT-CARRIER DETECTOR AND SWITCHING DIODES



PLASTIC SOD-323 CASE 477



ORDERING INFORMATION

Device	Package	Shipping
MMDL301T1	SOD-323	3000 / Tape & Reel

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I _R = 10 μA)	V(BR)R	30	_	_	Volts
Total Capacitance (V _R = 15 V, f = 1.0 MHz) Figure 1	CT	_	0.9	1.5	pF
Reverse Leakage (V _R = 25 V) Figure 3	IR	_	13	200	nAdc
Forward Voltage (I _F = 1.0 mAdc) Figure 4	٧F	_	0.38	0.45	Vdc
Forward Voltage (I _F = 10 mAdc) Figure 4	٧F	_	0.52	0.6	Vdc

TYPICAL ELECTRICAL CHARACTERISTICS

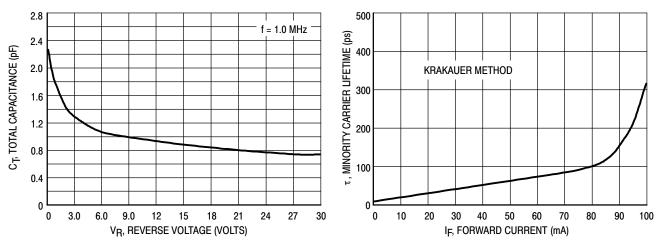


Figure 1. Total Capacitance

Figure 2. Minority Carrier Lifetime

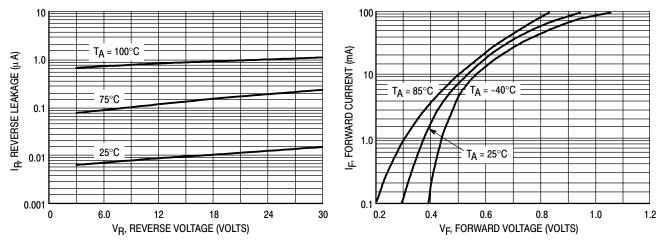


Figure 3. Reverse Leakage

Figure 4. Forward Voltage

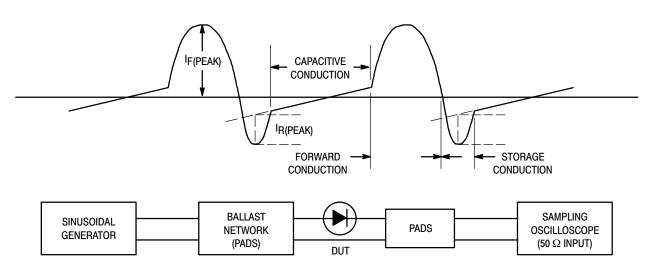
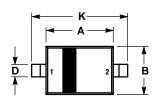


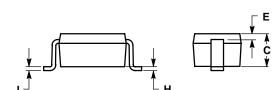
Figure 5. Krakauer Method of Measuring Lifetime

PACKAGE DIMENSIONS



NOTE 3

SOD-323 PLASTIC PACKAGE CASE 477-02 **ISSUE A**



- NOTES:

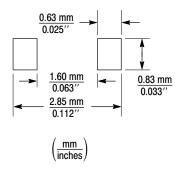
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	1.60	1.80	0.063	0.071	
В	1.15	1.35	0.045	0.053	
C	0.80	1.00	0.031	0.039	
D	0.25	0.40	0.010	0.016	
Е	0.15 REF		0.006 REF		
Н	0.00	0.10	0.000	0.004	
7	0.089	0.177	0.0035	0.0070	
K	2.30	2.70	0.091	0.106	

STYLE 1: PIN 1. CATHODE 2. ANODE



SOD-323 Soldering Footprint

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